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1. Features



Schematic

Pin Configuration
1. Anode
2. Cathode
3. Emitter
4. Collector

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2. Description

-10

4-

3.Applications

	Parameter	Symbol	Rated Value	Unit
			60	
			125	
			6	
			100	
			0	
			7	
			50	
			150	
			250	
*1			5000	
			-55 + 110	3
			-55 + 125	
*2			260	

, . . 40 60% . . 1, 2

3, 4

* 2 10



5. Electrical Optical Characteristics at Ta=25°C

	Parameter	Symbol	Condition	Min	Typ.*	Max	Unit
			50		1.25	1.6	
			4			10	
			0, 1		50		
			20 ,		10	100	
			1 0	0			
			0.1	7			
			5	50		600	%
			5	2.5		30	
		()	10 1			0.3	
			500 40 60%	1012			
			0, 1		0.3		
			5,		3	1	
			100		4.7	1	

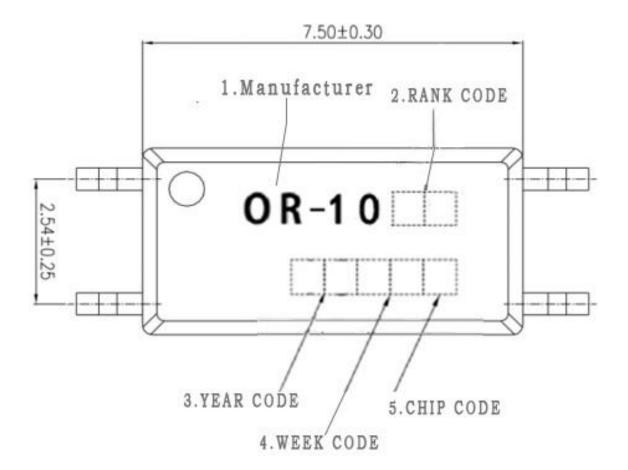


6. Rank Table of Current Transfer Ratio

3



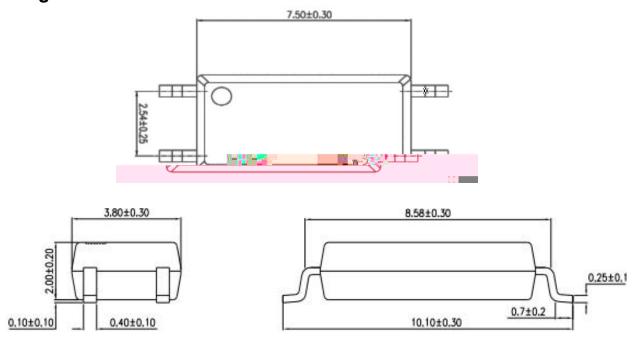
7.Naming Rule



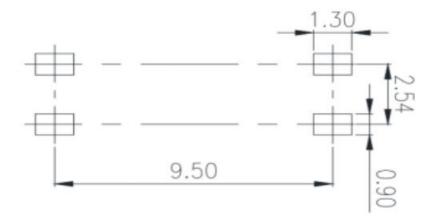




8. Package Dimension

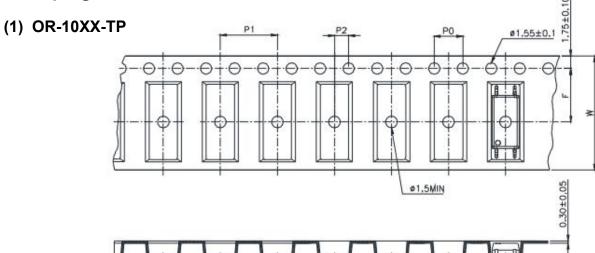


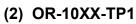
9.RRECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)

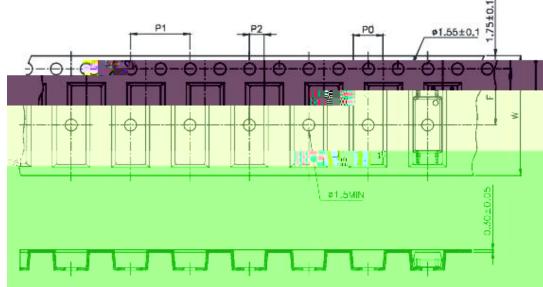


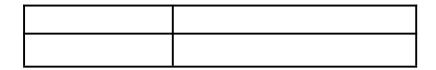


10. Taping Dimensions





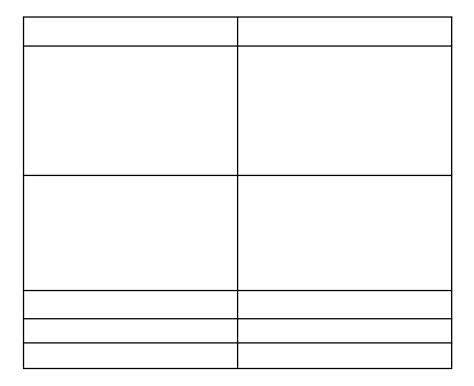


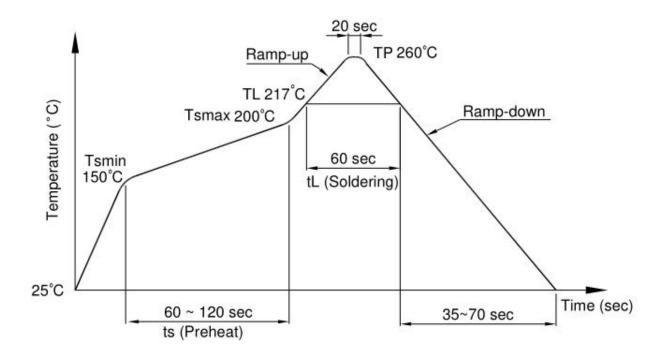




11.Temperature Profile Of Soldering

(1).IR Reflow soldering (JEDEC-STD-020C compliant)

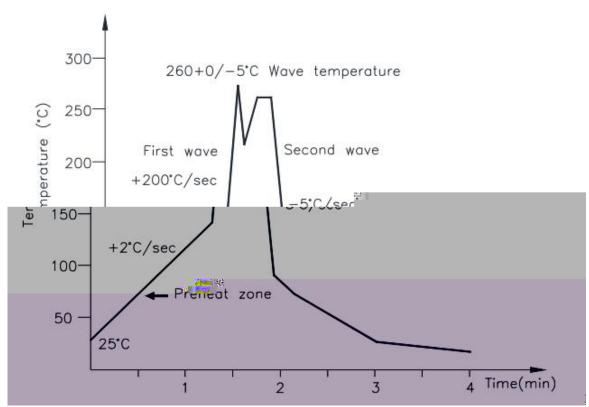






(2). Wave soldering (JEDEC22A111 compliant)



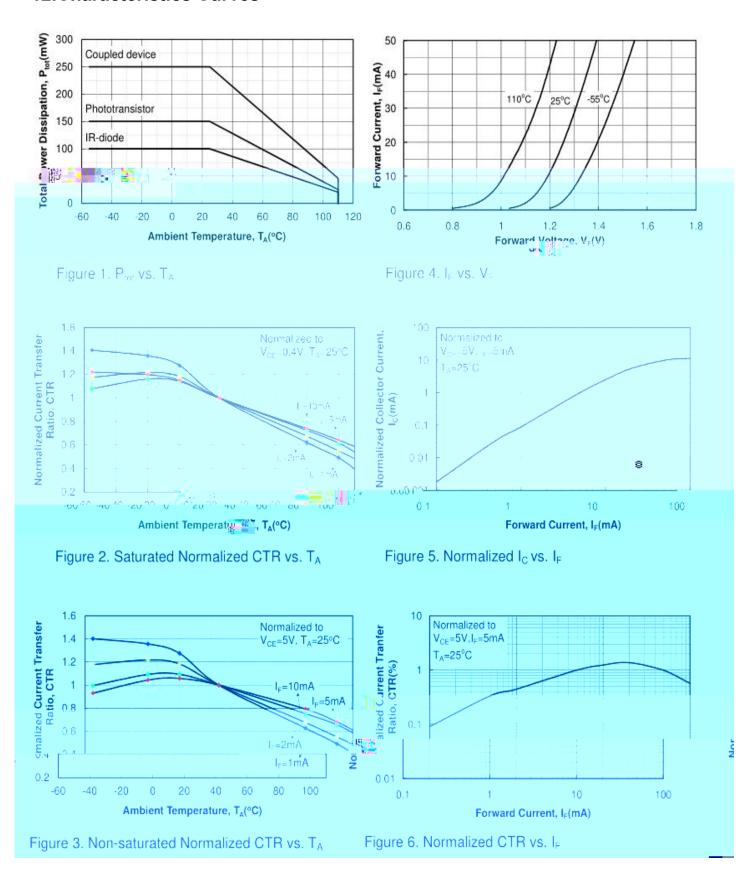


(3). Hand soldering by soldering iron

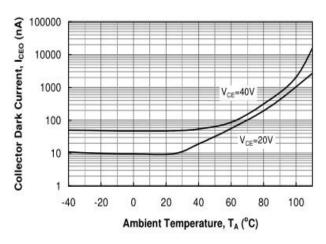




12. Characteristics Curves







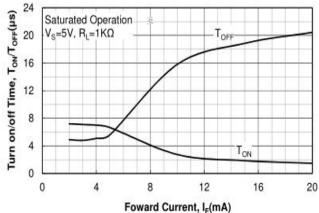
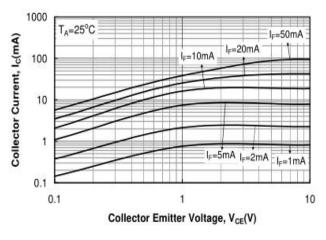


Figure 7. I_{CEO} vs. T_A

Figure 10. Ton / Toff vs. If



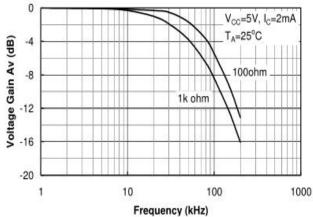


Figure 8. I_C vs. V_{CE}

Figure 11. Frequency Response

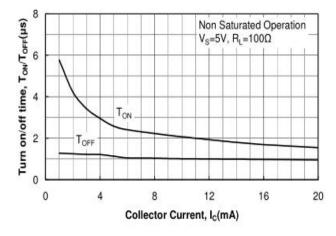


Figure 9 - 1777 FF vs. Ic



► Notes: